

TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

## TD62703P,TD62703F

### 6CH HIGH VOLTAGE SOURCE DRIVER

The TD62703P, TD62703F is comprised of six source current Transistor Array.

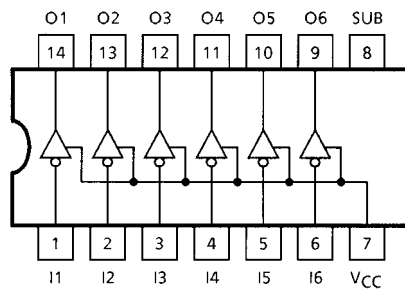
These drivers are specifically designed for fluorescent display applications.

For proper operation, the substrate (SUB) must be connected to the most negative voltage.

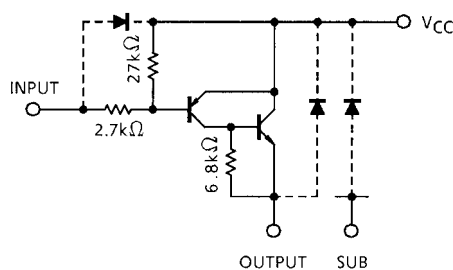
### FEATURES

- High output voltage :  $V_{CC}, V_{OUT} = 60\text{ V (Min)}$
- Output current (single output) :  $I_{OUT} = -50\text{ mA (Max)}$
- Input resistor :  $R_{IN} = 2.7\text{ k}\Omega$
- Package type-P : DIP-14 pin
- Package type-F : SOP-14 pin

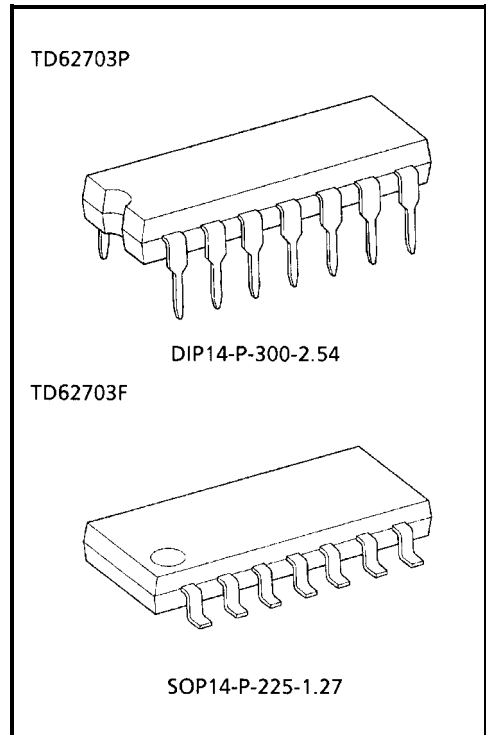
### PIN CONNECTION (TOP VIEW)



### SCHEMATICS (EACH DRIVER)



Note: The input and output parasitic diodes cannot be used as clamp diodes.



Weight

DIP14-P-300-2.54 : 1.11 g (Typ.)

SOP14-P-225-1.27 : 0.16 g (Typ.)

**MAXIMUM RATINGS (Ta = 25°C)**

CHARACTERISTIC		SYMBOL	RATING	UNIT
Supply Voltage		V <sub>SUB</sub>	V <sub>CC</sub> - 60	V
Output Sustaining Voltage		V <sub>OUT</sub>	V <sub>CC</sub> - 60	V
Input Voltage		V <sub>IN</sub>	-30~0.5	V
Output Current		I <sub>OUT</sub>	-50	mA / ch
Input Current		I <sub>IN</sub>	10	mA
Power Dissipation	P	P <sub>D</sub> (Note 2)	1.0	W
	F		0.625 (Note 1)	
Operating Temperature		T <sub>opr</sub>	-40~85	°C
Storage Temperature		T <sub>stg</sub>	-55~150	°C

Note 1: On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 50%)

Note 2: Delated above 25°C in the proportion 8.0mW / °C (P Type), 5.0mW / °C (F Type).

**RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C)**

CHARACTERISTIC		SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT
Supply Voltage		V <sub>SUB</sub>	V <sub>CC</sub> = 0 V	V <sub>OUT</sub>	—	-55	V
Output Sustaining Voltage		V <sub>OUT</sub>		0	—	V <sub>SUB</sub>	V
Output Current		I <sub>OUT</sub>		0	—	-40	mA / ch
Input Voltage		V <sub>IN</sub>		0	—	-7.0	V
Power Dissipation	P	P <sub>D</sub>	—	—	—	0.36	W
	F		On PCB (Note)	—	—	0.325	

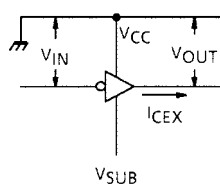
Note: On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 30%)

**ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

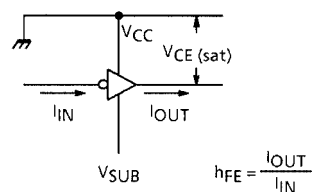
CHARACTERISTIC		SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Output Leakage Current		I <sub>CEX</sub>	1	V <sub>CC</sub> = 0 V, V <sub>IN</sub> = 0 V V <sub>OUT</sub> = -55 V	—	—	-100	μA
Collector-Emitter Saturation Voltage		V <sub>CE (sat)</sub>	2	I <sub>IN</sub> = -1 mA, I <sub>OUT</sub> = -40 mA	—	—	-2.5	V
DC Current Transfer Ratio		h <sub>FE</sub>	2	V <sub>CE</sub> = -5.0 V, I <sub>OUT</sub> = -40 mA	100	—	—	—
Input Current	Output On	V <sub>IN (ON)</sub>	3	V <sub>CC</sub> = 0 V, V <sub>IN</sub> = -5.1 V	—	-1.7	-2.4	mA
	Output Off	V <sub>IN (OFF)</sub>		—	—	—	10	μA
Input Voltage	Output On	V <sub>IN (ON)</sub>	4	V <sub>CC</sub> = 0 V	-3.0	—	—	V
	Output Off	V <sub>IN (OFF)</sub>			—	—	-0.44	
Turn-On Delay	P	t <sub>ON</sub>	5	V <sub>CC</sub> = 0 V, V <sub>SUB</sub> = V <sub>OUT</sub> = -55 V R <sub>L</sub> = 1.4 kΩ, C <sub>L</sub> = 15 pF	—	1	—	μs
	F				—	0.5	—	
Turn-Off Delay	P	t <sub>ON</sub>			—	2	—	μs
	F				—	1	—	

## TEST CIRCUIT

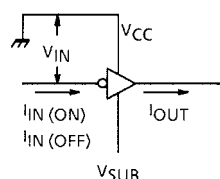
### 1. $I_{CEX}$



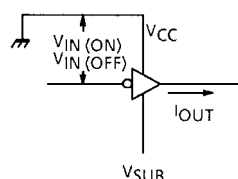
### 2. $V_{CE(sat)}$ , $h_{FE}$



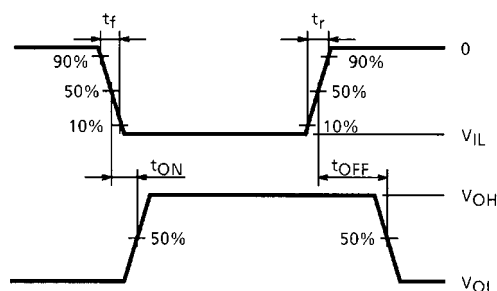
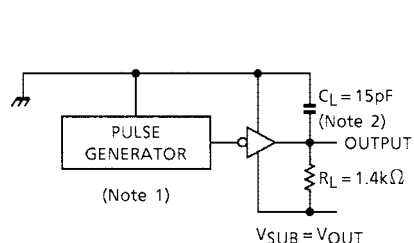
### 3. $I_{IN(ON)}$ , $I_{IN(OFF)}$



### 4. $V_{IN(ON)}$ , $V_{IN(OFF)}$



### 5. $t_{ON}$ , $t_{OFF}$

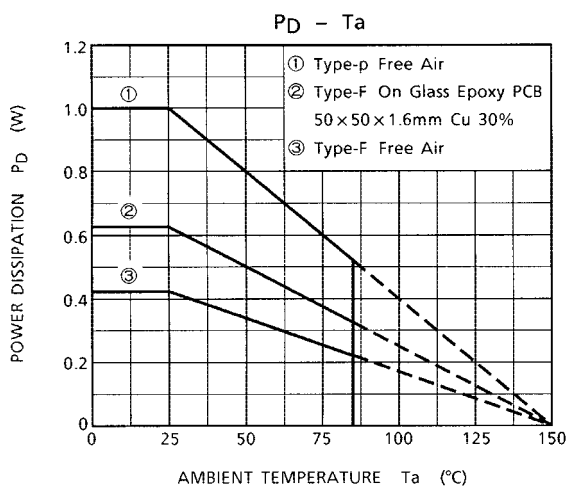
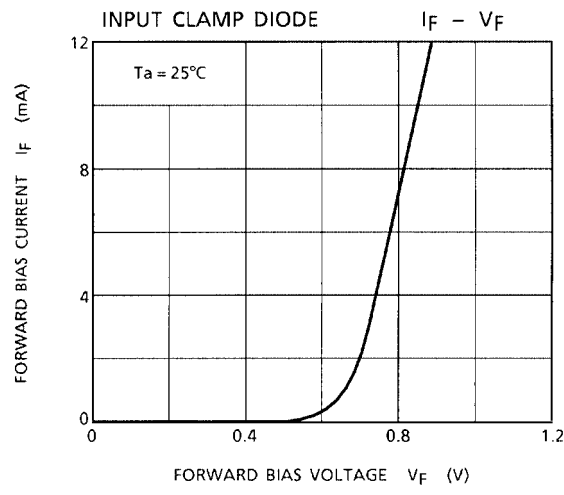
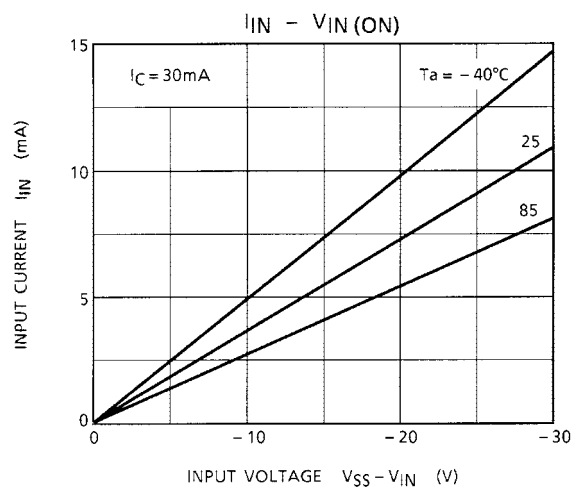


Note 1: Pulse width 50  $\mu$ s, Duty Cycle 10%  
Output Impedance 50  $\Omega$ ,  $t_r \leq 10$  ns,  $t_f \leq 5$  ns  
Note 2:  $C_L$  includes probe and jig capacitance.

## PRECAUTIONS for USING

This IC does not integrate protection circuits such as overcurrent and overvoltage protectors. Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

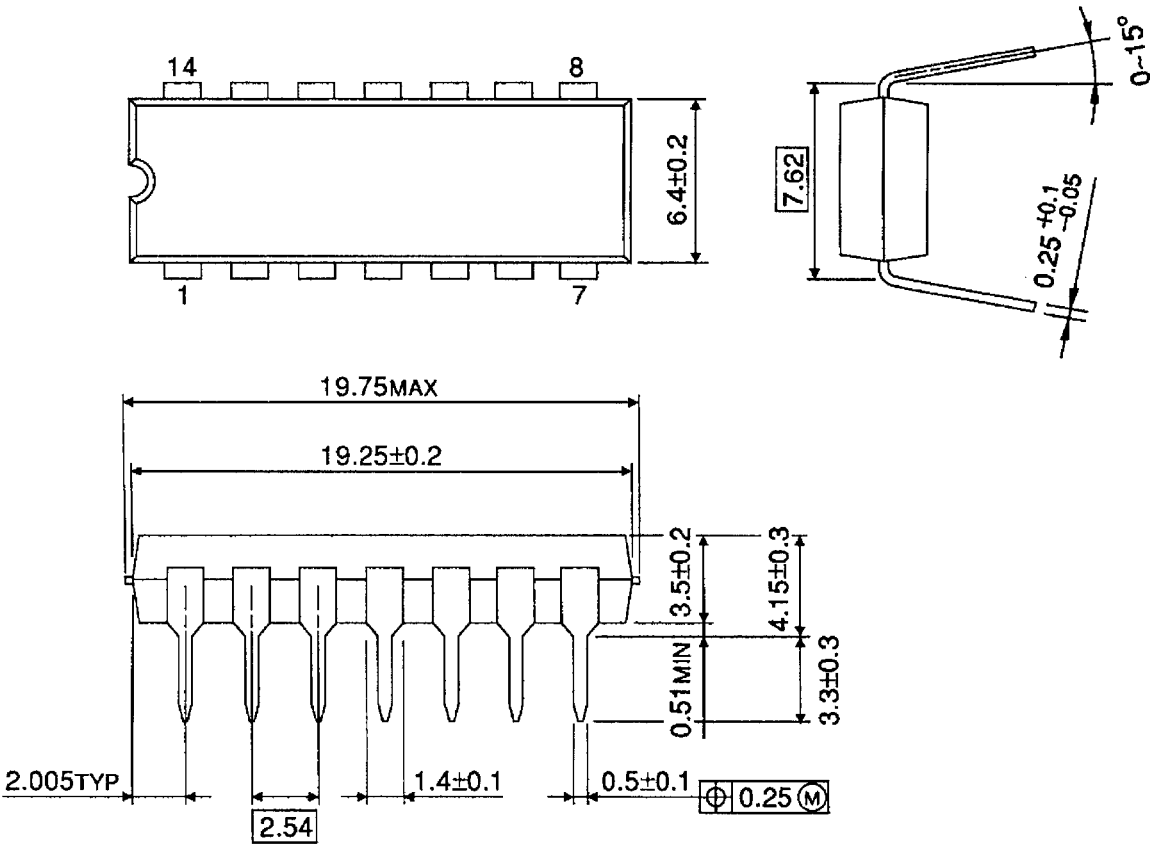
Utmost care is necessary in the design of the output line, VCC and GND (SUB) line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.



PACKAGE DIMENSIONS

DIP14-P-300-2.54

Unit: mm

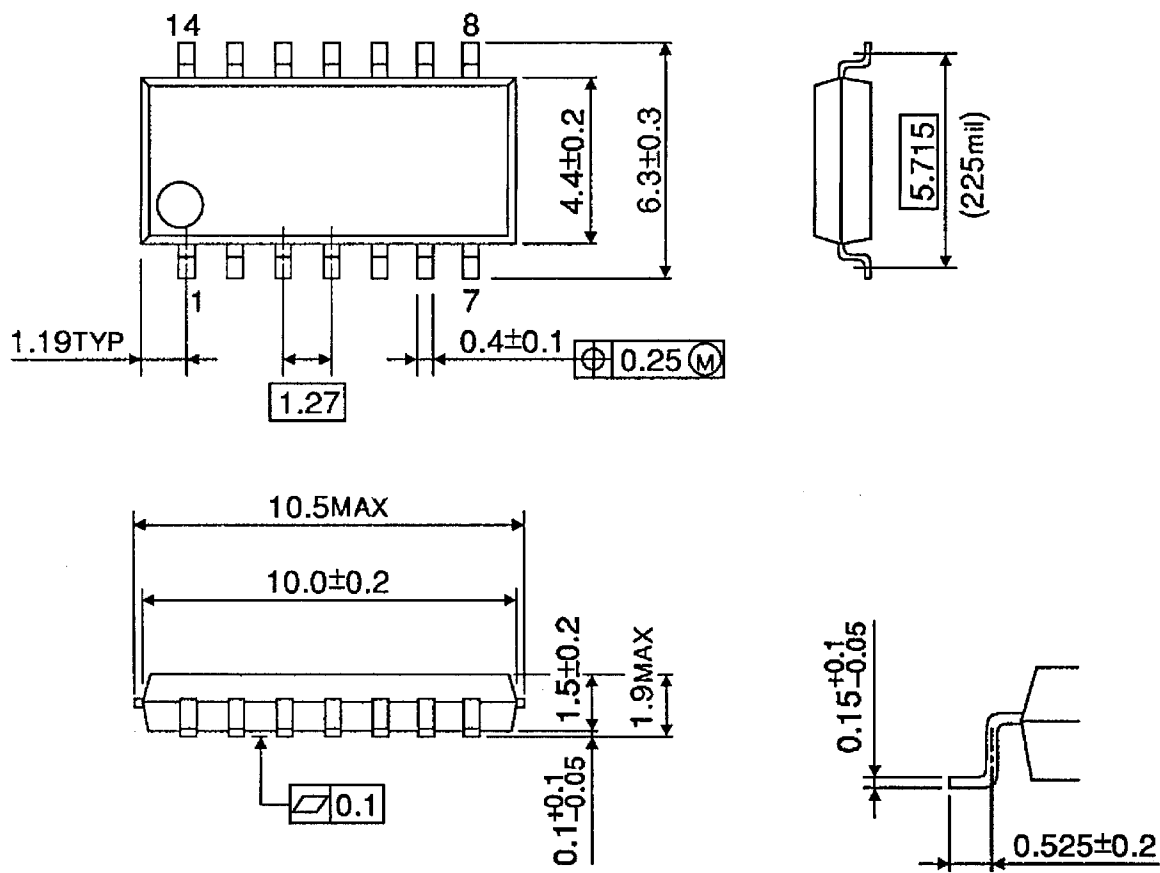


Weight: 1.11 g (Typ.)

PACKAGE DIMENSIONS

SOP14-P-225-1.27

Unit: mm



Weight: 0.16 g (Typ.)

**RESTRICTIONS ON PRODUCT USE**

000707EBA

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Datasheets for electronics components.